DELIVERY SPECIFICATION

SPEC. No.
DATE : Sep., 2025

To

CUSTOMER'S PRODUCT NAME	TDK PRODUCT NAME
	Multilayer Ceramic Chip Capacitors (Mega cap CA series) Tape packaging【RoHS2 compliant】 CAA572,CAA573 type X7R,X7S,X7T,X6T Characteristics

Please return this specification to TDK representatives with your signature.
If orders are placed without returned specification, please allow us to judge that specification is accepted by your side.

RECEIPT CONFIRMATION

DATE: YEAR MONTH DAY

TDK Corporation
Sales
Electronic Components
Sales & Marketing Group

Engineering
Electronic Components Business Company
Ceramic Capacitors Business Group

APPROVED	Person in charge

APPROVED	CHECKED	Person in charge

SCOPE

This delivery specification shall be applied to Multilayer ceramic chip capacitors (Mega cap CA series) ____________________.

PRODUCTION PLACES

Production places defined in this specification shall be TDK Corporation, TDK(Suzhou)Co.,Ltd
TDK Xiamen Co.,Ltd, and TDK Components U.S.A.Inc.

PRODUCT NAME

The name of the product to be defined in this specifications shall be CAA57◇○○○△△□□□× .

REFERENCE STANDARD

JIS	C 5101－1 : 2010	Fixed capacitors for use in electronic equipment-Part 1: Generic specification
	C 5101－22 : 2014	Fixed capacitors for use in electronic equipment-Part22 : Sectional specification : Fixed surface mount multilayer capacitors of ceramic dielectric,Class 2
	C 0806－3 : 2014	Packaging of components for automatic handling - Part 3: Packaging of surface mount components on continuous tapes
JEITA	RCR－2335 C 2014	Safety application guide for fixed ceramic capacitors for use in electronic equipment

COONTENTS

<EXPLANATORY NOTE>

When the mistrust in the spec arises, this specification is given priority. And it will be confirmed by written spec change after conference of both posts involved.
This specification warrants the quality of the ceramic chip capacitor. Capacitors should be evaluated or confirmed a state of mounted on your product.
If the use of the capacitors goes beyond the bounds of this specification, we can not afford to guarantee.

Division	Date	SPEC. No.
Ceramic Capacitors Business Group	September, 2025	

1. CODE CONSTRUCTION

(Example)	CA	A	57	3	X7S	2A	476	M	T	OOOO
	(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)	(10)

(1) Series

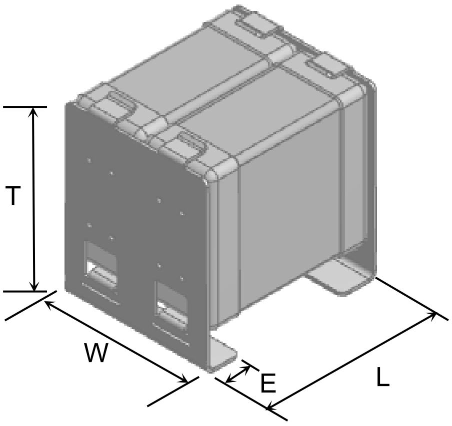
Symbol	Series
CA	Mega cap CA series

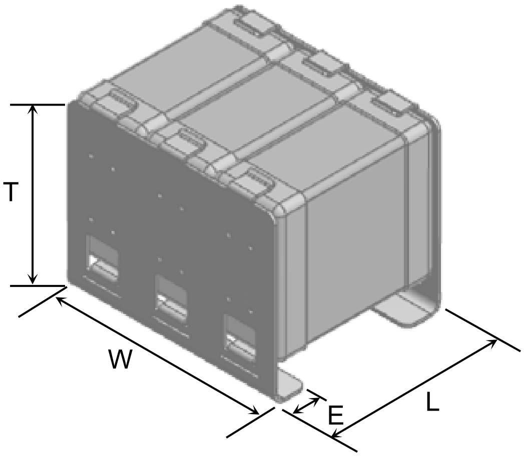
(2) TDK's auxiliary code

(3) Type

CAA572 : 2 side-by-side alignment type

CAA573 : 3 side-by-side alignment type





Type	Structure Symbol	Dimensions (Unit : mm)			
		L	W	T	E
57	2	6.00±0.50	5.00±0.50	6.40±0.50	1.20±0.20
		6.25±0.50	5.00±0.50	6.70±0.50	1.20±0.20
57	3	6.00±0.50	7.50±0.50	6.40±0.50	1.20±0.20
		6.25±0.50	7.50±0.50	6.70±0.50	1.20±0.20

* As for each item, please refer to detail page on TDK web.

(4) Structure

Symbol	Structure
2	2 side-by-side alignment type
3	3 side-by-side alignment type

(5) Temperature Characteristics

* Details are shown in table 1 No.6 at 5.PERFORMANCE.

(6) Rated Voltage

Symbol	Rated Voltage
2 J	DC 630 V
2 W	DC 450 V
2 V	DC 350 V
2 A	DC 100 V

Symbol	Rated Voltage
1 H	DC 50 V
1 V	DC 35 V
1 E	DC 25 V

(7) Rated Capacitance

Stated in three digits and in units of pico farads (pF). The first and second digits identify the first and second significant figures of the Capacitance, the third digit identifies the multiplier.

(Example)

Symbol	Rated Capacitance
476	47,000,000 pF

(8) Capacitance tolerance

Symbol	Tolerance
M	± 20 %

(9) Packaging

Symbol	Packaging
T	Taping

(10) TDK internal code

2. OPERATING TEMPERATURE RANGE

T.C.	Min. operating Temperature	Max. operating Temperature	Reference Temperature
X7R/X7S/X7T	-55°C	125°C	25°C
X6T	-55°C	105°C	25°C

3. STORING CONDITION AND TERM

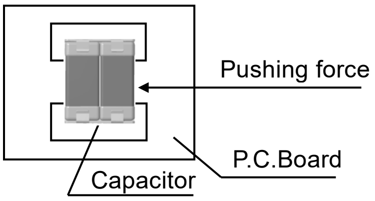
Storing temperature	Storing humidity	Storing term
5~40°C	20~70%RH	Within 6 months upon receipt.

4. INDUSTRIAL WASTE DISPOSAL

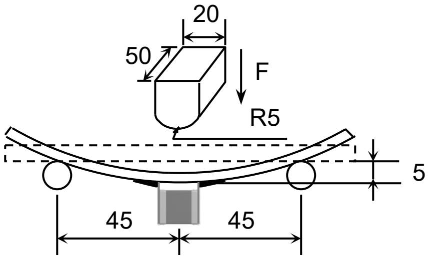
Dispose this product as industrial waste in accordance with the Industrial Waste Law.

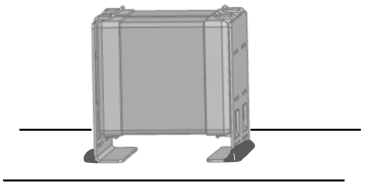
5. PERFORMANCE

Table 1

<table>
<tr><th>No.</th><th>Item</th><th>Performance</th><th>Test or inspection method</th></tr>
<tr><td>1</td><td>External Appearance</td><td>No defects which may affect performance.</td><td>Inspect with magnifying glass(3×)</td></tr>
<tr><td>2</td><td>Insulation Resistance</td><td>500MΩ·μF min.</td><td>Measuring voltage : Rated voltage
(As for the capacitor of rated voltage 630V DC, apply 500V DC.)
Voltage application time : 60s.</td></tr>
<tr><td>3</td><td>Voltage Proof</td><td>Withstand test voltage without insulation breakdown or other damage.</td><td>
<table>
<tr><th>Rated voltage(RV)</th><th>Apply voltage</th></tr>
<tr><td>RV ≦ 100V</td><td>2.5 × rated voltage</td></tr>
<tr><td>100V＜RV≦500V</td><td>1.5 × rated voltage</td></tr>
<tr><td>500V＜RV</td><td>1.3 × rated voltage</td></tr>
</table>
Voltage application time : 1s.
Charge / discharge current : 50mA or lower</td></tr>
<tr><td>4</td><td>Capacitance</td><td>Within the specified tolerance.</td><td>
<table>
<tr><th>Capacitance</th><th>Measuring frequency</th><th>Measuring voltage</th></tr>
<tr><td>10μF and under</td><td>1kHz±10%</td><td>1.0±0.2Vrms.</td></tr>
<tr><td>Over 10μF</td><td>120Hz±20%</td><td>0.5±0.2Vrms.</td></tr>
</table>
</td></tr>
<tr><td>5</td><td>Dissipation Factor</td><td>Please refer to detail page on TDK web.</td><td>See No.4 in this table for measuring condition.</td></tr>
<tr><td>6</td><td>Temperature Characteristics of Capacitance</td><td>
<table>
<tr><th>Capacitance Change (%)</th></tr>
<tr><td>No voltage applied</td></tr>
<tr><td>X7R : ± 15
X7S : ± 22
X7T : $^{+22}_{-33}$
X6T : $^{+22}_{-33}$</td></tr>
</table>
</td><td>Capacitance shall be measured by the steps shown in the following table after thermal equilibrium is obtained for each step.
ΔC be calculated ref. STEP3 reading
<table>
<tr><th>Step</th><th>Temperature(°C)</th></tr>
<tr><td>1</td><td>Reference temp. ± 2</td></tr>
<tr><td>2</td><td>Min. operating temp. ± 2</td></tr>
<tr><td>3</td><td>Reference temp. ± 2</td></tr>
<tr><td>4</td><td>Max. operating temp. ± 2</td></tr>
</table>
As for Min./ Max. operating temp. and Reference temp., please refer to "2.OPERATING TEMPERATURE RANGE".
As for measuring voltage, please contact with our sales representative.</td></tr>
<tr><td>7</td><td>Robustness of Terminations</td><td>No sign of termination coming off, breakage of ceramic, or other abnormal signs.</td><td>Reflow solder the capacitors on a P.C.Board shown in Appendix 2.
Apply a pushing force gradually at the center of a specimen in a horizontal direction of P.C.board.
Pushing force : 5N
Holding time : 10±1s.
 </td></tr>
</table>

(continued)

<table>
<tr><th>No.</th><th colspan="2">Item</th><th>Performance</th><th>Test or inspection method</th></tr>
<tr><td>8</td><td>Bending</td><td>External appearance</td><td>No mechanical damage.</td><td>Reflow solder the capacitor on a P.C.Board shown in Appendix1.


（Unit : mm）</td></tr>
<tr><td>9</td><td colspan="2">Solderability</td><td>Both end faces and the contact areas shall be covered with a smooth and bright solder coating with no more than a small amount of scattered imperfections such as pinholes or un-wetted or de-wetted areas.
These imperfections shall not be concentrated in one area.
</td><td>Solder : Sn-3.0Ag-0.5Cu

Reflow solder the capacitor on a P.C.Board shown in Appendix2.

Please refer to No.5 Soldering in 10.CAUTION for soldering condition.</td></tr>
<tr><td rowspan="3">10</td><td rowspan="3">Vibration</td><td>External appearance</td><td>No mechanical damage.</td><td rowspan="3">Frequency : 10~55~10Hz
Reciprocating sweep time : 1 min.
Amplitude : 1.5mm
Repeat this for 2h each in 3 perpendicular directions(Total 6h).

Reflow solder the capacitors on a P.C.Board shown in Appendix2 before testing.</td></tr>
<tr><td>Capacitance</td><td><table><tr><th>Characteristics</th><th>Change from the value before test</th></tr><tr><td>X7R
X7S
X7T
X6T</td><td>± 7.5 %</td></tr></table></td></tr>
<tr><td>D.F.</td><td>Meet the initial spec.</td></tr>
<tr><td rowspan="5">11</td><td rowspan="5">Temperature cycle</td><td>External appearance</td><td>No mechanical damage.</td><td rowspan="5">Expose the capacitors in the condition step1 through step 4 listed in the following table.

Temp. cycle : 100 cycles<table><tr><th>Step</th><th>Temperature(°C)</th><th>Time(min.)</th></tr><tr><td>1</td><td>Min. operating temp. ±3</td><td>30 ± 3</td></tr><tr><td>2</td><td>Ambient Temp.</td><td>2～5</td></tr><tr><td>3</td><td>Max. operating temp. ±2</td><td>30 ± 2</td></tr><tr><td>4</td><td>Ambient Temp.</td><td>2～5</td></tr></table>As for Min./ Max. operating temp., please refer to "2.OPERATING TEMPERATURE RANGE".
Leave the capacitors in ambient condition for 24±2h before measurement.

Reflow solder the capacitors on a P.C.Board shown in Appendix2 before testing.</td></tr>
<tr><td>Capacitance</td><td><table><tr><th>Characteristics</th><th>Change from the value before test</th></tr><tr><td>X7R
X7S
X7T
X6T</td><td>Please contact with our sales representative.</td></tr></table></td></tr>
<tr><td>D.F.</td><td>Meet the initial spec.</td></tr>
<tr><td>Insulation Resistance</td><td>Meet the initial spec.</td></tr>
<tr><td>Voltage proof</td><td>No insulation breakdown or other damage.</td></tr>
</table>

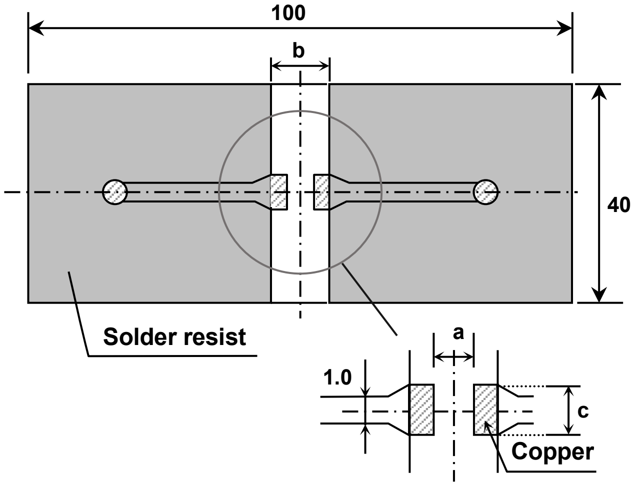
(continued)

<table>
<tr><th>No.</th><th colspan="2">Item</th><th>Performance</th><th>Test or inspection method</th></tr>
<tr><td rowspan="4">12</td><td rowspan="4">Moisture Resistance</td><td>External appearance</td><td>No mechanical damage.</td><td rowspan="4">Test temp. ：40±2°C
Test humidity ：90~95%RH
Applied voltage ：Rated voltage
Test time ：500 +24,0h
Charge/discharge current ：50mA or lower
Leave the capacitors in ambient condition for 24 ± 2h before measurement.
Reflow solder the capacitors on a P.C.Board shown in Appendix2 before testing.
Initial value setting
Voltage conditioning《After voltage treat the capacitors under testing temperature and voltage for 1 hour,》leave the capacitors in ambient condition for 24±2h before measurement.
Use this measurement for initial value.</td></tr>
<tr><td>Capacitance</td><td><table><tr><th>Characteristics</th><th>Change from the value before test</th></tr><tr><td>X7R
X7S
X7T
X6T</td><td>Please contact with our sales representative.</td></tr></table></td></tr>
<tr><td>D.F.</td><td>200% of initial spec max.</td></tr>
<tr><td>Insulation Resistance</td><td>25MΩ·μF min.</td></tr>
<tr><td rowspan="4">13</td><td rowspan="4">Life</td><td>External appearance</td><td>No mechanical damage.</td><td rowspan="4">Test temp. ：Maximum operating temperature±2°C
Applied voltage ：Please contact with our sales representative.
Test time ：1,000 +48,0h
Charge/discharge current ：50mA or lower
Leave the capacitors in ambient condition for 24 ± 2h before measurement.
Reflow solder the capacitors on a P.C.Board shown in Appendix2 before testing.
Initial value setting
Voltage conditioning《After voltage treat the capacitors under testing temperature and voltage for 1 hour,》leave the capacitors in ambient condition for 24±2h before measurement.
Use this measurement for initial value.</td></tr>
<tr><td>Capacitance</td><td><table><tr><th>Characteristics</th><th>Change from the value before test</th></tr><tr><td>X7R
X7S
X7T
X6T</td><td>Please contact with our sales representative.</td></tr></table></td></tr>
<tr><td>D.F.</td><td>200% of initial spec max.</td></tr>
<tr><td>Insulation Resistance</td><td>50MΩ·μF min.</td></tr>
</table>

∗As for the initial measurement of capacitors on number 6,10 and 11 leave capacitors at 150 0,–10°C for 1h and measure the value after leaving capacitors for 24±2h in ambient condition.

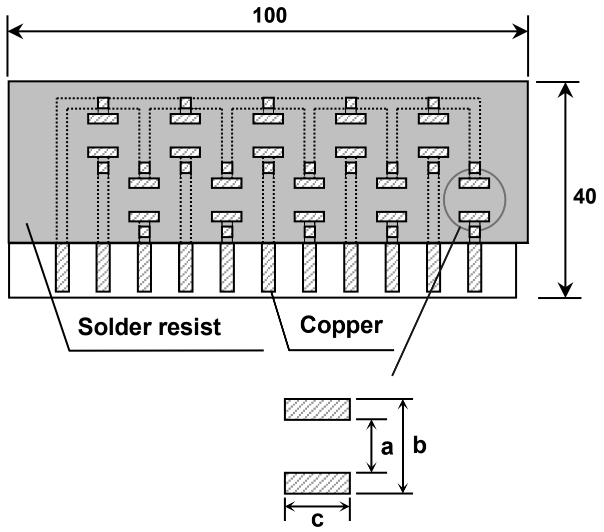
Appendix1

P.C.Board for bending test



Appendix 2

P.C. Board for reliability test



（Unit : mm）

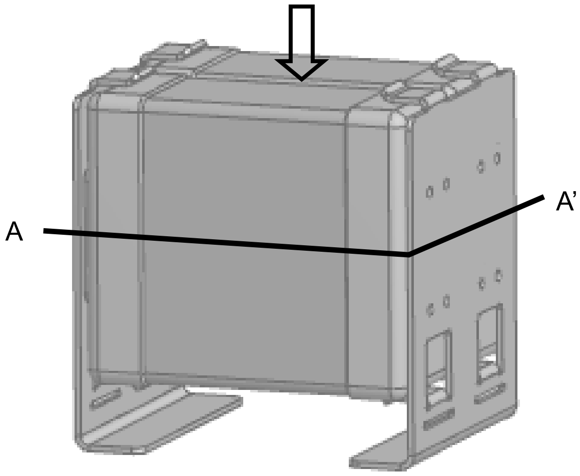
Symbol Case size	a	b	c
CAA572	4.5	8.0	5.6
CAA573	4.5	8.0	8.1

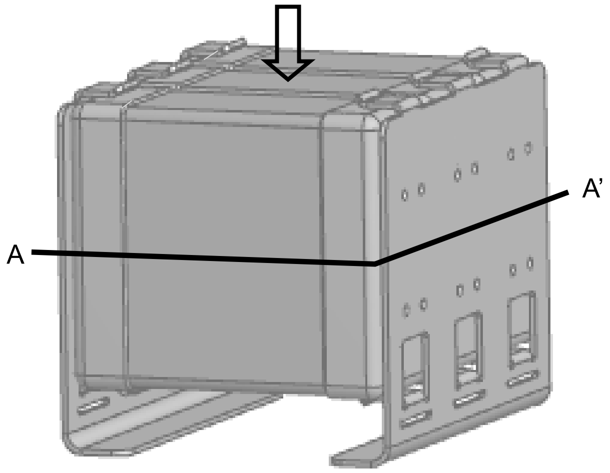
1. Material : Glass Epoxy(As per JIS C6484 GE4)

2. Thickness : 1.6mm

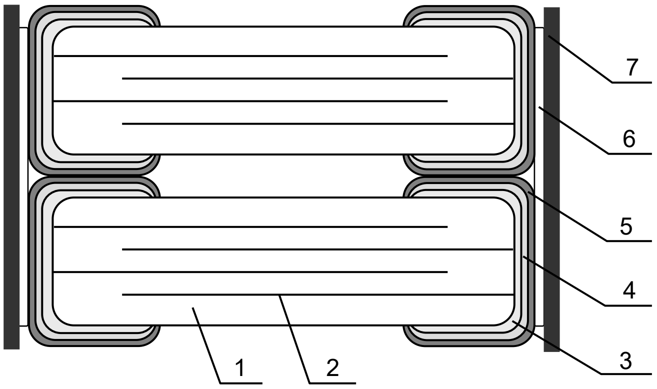
▨ Copper(Thickness:0.035mm)
■ Solder resist

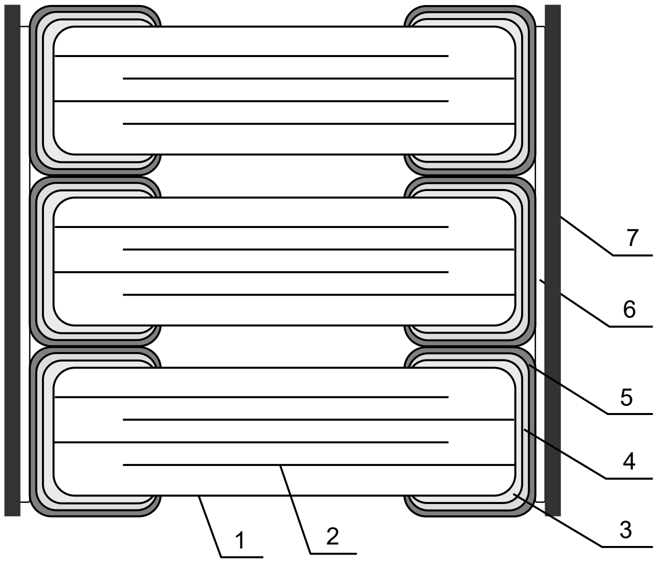
6. INSIDE STRUCTURE AND MATERIAL





A－A’





No.	NAME	MATERIAL
1	Dielectric	$BaTiO_3$
2	Electrode	Nickel (Ni)
3	Termination	Copper (Cu)
4		Nickel (Ni)
5		Tin (Sn)
6	Metal cap joint	High temp solder
7	Metal cap	Clad

7. PACKAGING

Packaging shall be done to protect the components from the damage during transportation and storing, and a label which has the following information shall be attached.
Tape packaging is as per 11. TAPE PACKAGING SPECIFICATION.

1) Inspection No.
2) TDK P/N
3) Customer's P/N
4) Quantity

*Composition of Inspection No.

Example	F	5	A	–	2 3	–	0 0 1
	(a)	(b)	(c)		(d)		(e)

a) Line code
b) Last digit of the year
c) Month and A for January and B for February and so on. (Skip I)
d) Inspection Date of the month.
e) Serial No. of the day

*Composition of new Inspection No.
(Implemented on and after May 1, 2019 in sequence)

Example	I	F	5	E	2 3	A 0	0 1
	(a)	(b)	(c)	(d)	(e)	(f)	(g)

(a) Prefix
(b) Line code
(c) Last digit of the year
(d) Month and A for January and B for February and so on. (Skip I)
(e) Inspection Date of the month.
(f) Serial No. of the day(00 ~ ZZ)
(g) Suffix(00 ~ ZZ)

* It was shifted to the new inspection No. on and after May 2019, but the implementation timing may be different depending on shipment bases.
Until the shift is completed, either current or new composition of inspection No. will be applied.

8. RECOMMENDATION

It is recommended to provide a slit (about 1mm wide) in the board under the components to improve washing Flux.
And please make sure to dry detergent up completely before.

9. SOLDERING CONDITION

Reflow soldering only.
Please refer to No.5 Soldering in 10. CAUTION for recommended soldering condition.

10. CAUTION

No.	Process	Condition
1	Operating Condition (Storage, Use, Transportation)	1-1. Storage, Use The capacitors must be stored in an ambient temperature of 5 to 40°C with a relative humidity of 20 to 70%RH. JIS C 60721-3-1 Class 1K2 should be followed for the other climatic conditions. 1) High temperature and humidity environment may affect a capacitor's solder ability because it accelerates terminal oxidization. They also deteriorate performance of taping and packaging. Therefore, SMD capacitors shall be used within 6 months. For capacitors with terminal electrodes consisting of silver or silver-palladium which tend to become oxidized or sulfurized, use as soon as possible, such as within one month after opening the bag. 2) When capacitors are stored for a period longer than specified, confirm the solderability of the capacitors prior to use. During storage, keep the minimum packaging unit in its original packaging without opening it. Do not deviate from the above temperature and humidity conditions even for a short term. 3) Corrosive gasses in the air or atmosphere may result in deterioration of the reliability, such as poor solderability of the terminal electrodes. Do not store capacitors where they will be exposed to corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine ammonia etc.) 4) Solderability and electrical performance may deteriorate due to photochemical change in the terminal electrode if stored in direct sunlight, or due to condensation from rapid changes in humidity. The capacitors especially which use resin material must be operated and stored in an environment free of dew condensation, as moisture absorption due to condensation may affect the performance. 5) Refer to JIS C 60721-3-1, class 1K2 for other climate conditions. 1-2. Handling in transportation In case of the transportation of the capacitors, the performance of the capacitors may be deteriorated depending on the transportation condition. (Refer to JEITA RCR-2335C 9.2 Handling in transportation)
2	Circuit design ⚠ Caution	2-1. Operating temperature 1) Upper category temperature (maximum operating temperature) is specified. It is necessary to select a capacitor whose rated temperature us higher than the operating temperature. Also, it is necessary to consider the temperature distribution in the equipment and seasonal temperature variation. 2) Surface temperature including self heating should be below maximum operating temperature. Due to dielectric loss, capacitors will heat itself when AC is applied due to ESR. Especially at high frequencies, please be careful that the heat might be so extreme. Also, even if the surface temperature of the capacitor includes self-heating and is the maximum operating temperature or lower, excessive heating of the capacitor due to self-heating may cause deterioration of the characteristics and reliability of the capacitor. The self-heating temperature rise of the capacitor changes depending on the difference in heat radiation due to the mounting method to the device, the ambient temperature, the cooling method of the device, etc. As a guide, please consult us if the self-heating temperature rise of the capacitor in a natural convection environment at an ambient temperature of 25°C exceeds 20°C. When using in a high-frequency circuit or a circuit in which a capacitor generates heat, such as when a high-frequency ripple current flows, pay attention to the above precautions. (Note that accurate measurement may not be possible with self-heating measurement when the equipment applies cooling other than natural convection such as a cooling fan.)

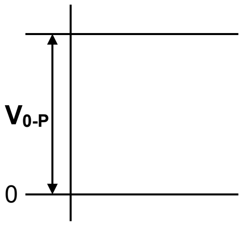
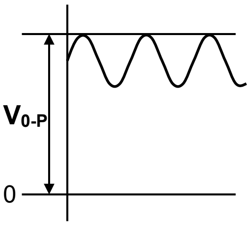
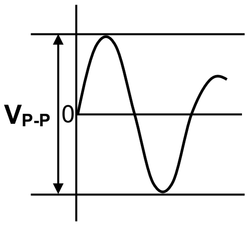
No.	Process	Condition
2	Circuit design ⚠ Caution	3) The electrical characteristics of the capacitors will vary depending on the temperature. The capacitors should be selected and designed in taking the temperature into consideration.

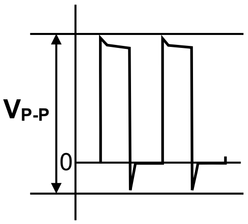
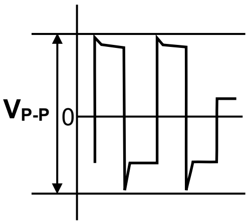
2-2. When overvoltage is applied

Applying overvoltage to a capacitor may cause dielectric breakdown and result in a short circuit. The duration until dielectric breakdown depends on the applied voltage and the ambient temperature.

2-3. Operating voltage

1) Operating voltage across the terminals should be below the rated voltage.
When AC and DC are super imposed, $V_{0\text{-}P}$ must be below the rated voltage.
— (1) and (2)
AC or pulse with overshooting, $V_{P\text{-}P}$ must be below the rated voltage.
— (3), (4) and (5)
When the voltage is started to apply to the circuit or it is stopped applying, the irregular voltage may be generated for a transit period because of resonance or switching. Be sure to use the capacitors within rated voltage containing these Irregular voltage.

Voltage	(1) DC voltage	(2) DC+AC voltage	(3) AC voltage
Positional Measurement (Rated voltage)			

Voltage	(4) Pulse voltage (A)	(5) Pulse voltage (B)
Positional Measurement (Rated voltage)		

2) Even below the rated voltage, if repetitive high frequency AC or pulse is applied, the reliability of the capacitors may be reduced.

3) The effective capacitance will vary depending on applied DC and AC voltages. The capacitors should be selected and designed in taking the voltages into consideration.

4) Abnormal voltage (surge voltage, static electricity, pulse voltage, etc.) shall not exceed the rated voltage.

5) When capacitors are used in a series connection, it is necessary to add a balancing circuit such as voltage dividing resistors in order to avoid an imbalance in the voltage applied to each capacitor.

2-4. Frequency

When the capacitors (Class 2) are used in AC and/or pulse voltages, the capacitors may vibrate themselves and generate audible sound.

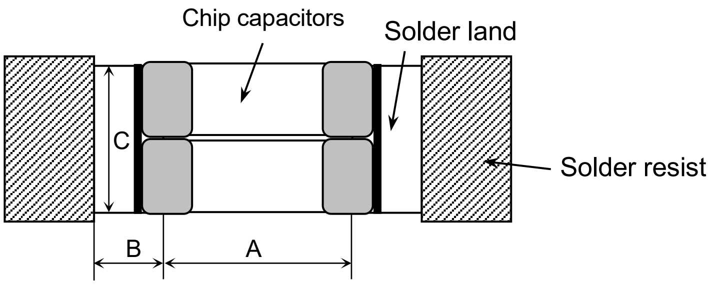
<table>
<tr><th>No.</th><th>Process</th><th>Condition</th></tr>
<tr><td>3</td><td>Designing
P.C.board</td><td>

The amount of solder at the terminations has a direct effect on the reliability of the capacitor.

1) The greater the amount of solder, the higher the stress on the chip capacitor, and the more likely that it will break. When designing a P.C.board, determine the shape and size of the solder lands to have proper amount of solder on the terminations.

2) Avoid using common solder land for multiple terminations and provide individual solder land for each terminations.

3) Size and recommended land dimensions.

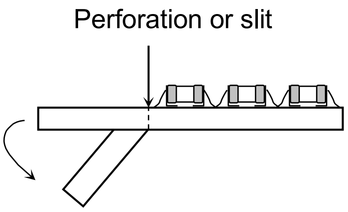
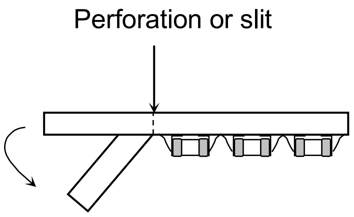
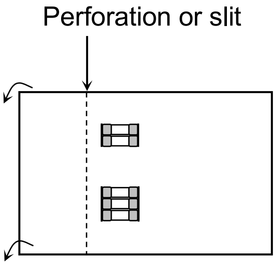
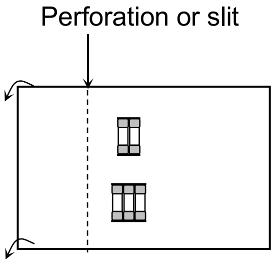
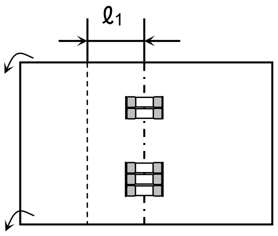
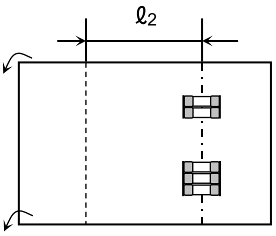


(Unit : mm)

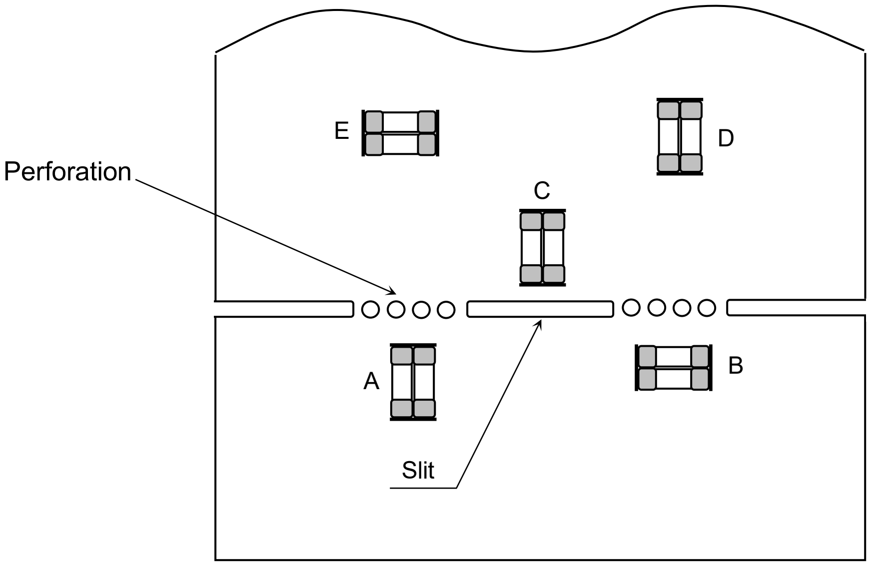
<table>
<tr><th>Case size
Symbol</th><th>CAA572</th><th>CAA573</th></tr>
<tr><td>A</td><td>4.3 ~ 4.7</td><td>4.3 ~ 4.7</td></tr>
<tr><td>B</td><td>1.5 ~ 2.0</td><td>1.5 ~ 2.0</td></tr>
<tr><td>C</td><td>5.2 ~ 5.7</td><td>7.9 ~ 8.4</td></tr>
</table>

</td></tr>
</table>

No.	Process	Condition
3	Designing P.C.board	4) Recommended chip capacitor layout is as following.

	Disadvantage against bending stress	Advantage against bending stress
Mounting face	 Break P.C.board with mounted side up.	 Break P.C.board with mounted side down.
Chip arrangement (Direction)	Mount perpendicularly to perforation or slit 	Mount in parallel with perforation or slit 
Distance from slit	Closer to slit is higher stress  $(\ell_1 < \ell_2)$	Away from slit is less stress  $(\ell_1 < \ell_2)$

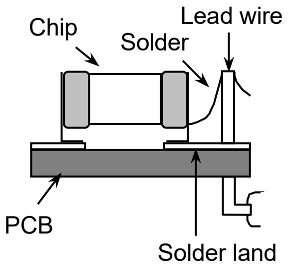
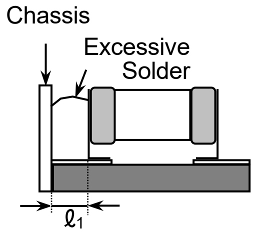
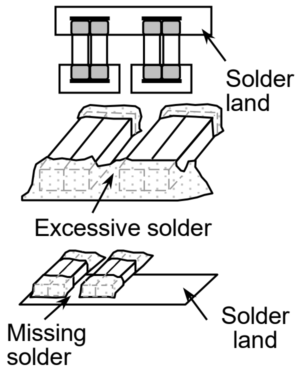
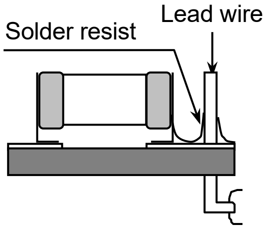
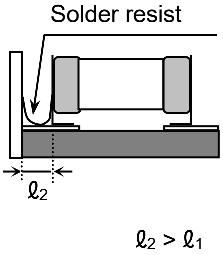
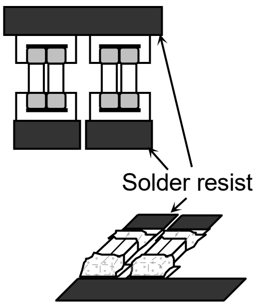
No.	Process	Condition
3	Designing P.C.board	5) Mechanical stress varies according to location of chip capacitors on the P.C.board.



Stress force
A>B>E
A>D>E
A>C

When dividing printed wiring boards, the intensities of mechanical stress applied to capacitors are different according to each dividing method in the order of : Push-back < Slit < V-groove < Perforation. Therefore consider not only position of capacitors, but also the way of the dividing the printed wiring boards.

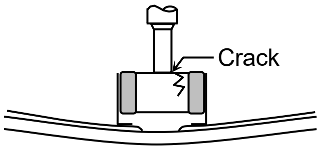
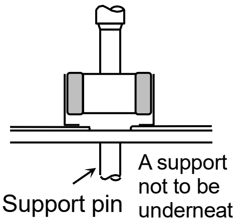
6) Layout recommendation

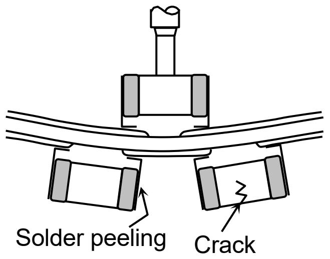
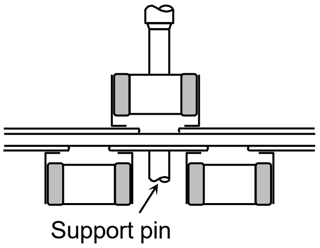
Example	Use of common solder land	Soldering with chassis	Use of common solder land with other SMD
Need to avoid			
Recommen-dation			

<table>
<tr><th>No.</th><th>Process</th><th>Condition</th></tr>
<tr><td>4</td><td>Mounting</td><td>
4-1. Stress from mounting head
If the mounting head is adjusted too low, it may induce excessive stress in the chip capacitor to result in cracking. Please take following precautions.

1) Adjust the bottom dead center of the mounting head to reach on the P.C.board surface and not press it.

2) Adjust the mounting head pressure to be 1 to 3N of static weight.

3) To minimize the impact energy from mounting head, it is important to provide support from the bottom side of the P.C.board.
See following examples.
<table>
<tr><th></th><th>Not recommended</th><th>Recommended</th></tr>
<tr><td>Single sided mounting</td><td>
</td><td>

A support pin is not to be underneath the capacitor.</td></tr>
<tr><td>Double-sides mounting</td><td>
</td><td>
</td></tr>
</table>
When the centering jaw is worn out, it may give mechanical impact on the capacitor to cause crack. Please control the close up dimension of the centering jaw and provide sufficient preventive maintenance and replacement of it.
</td></tr>
</table>

No.	Process	Condition
5	Soldering	5-1. Flux selection

Flux can seriously affect the performance of capacitors. Confirm the following to select the appropriate flux.

1) It is recommended to use a mildly activated rosin flux (less than 0.1wt% chlorine). Strong flux is not recommended.

2) Excessive flux must be avoided. Please provide proper amount of flux.

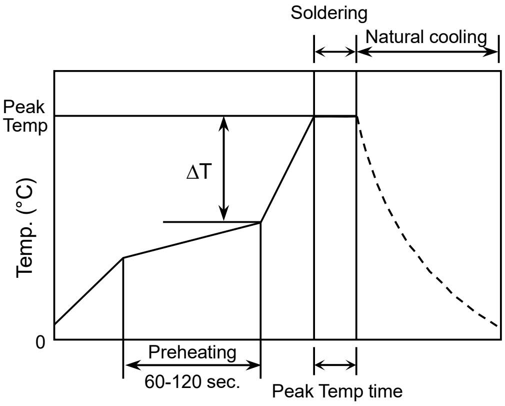
3) When water-soluble flux is used, enough washing is necessary.

5-2. Recommended Reflow soldering profile

1) Soldering condition (Preheating temperature, soldering temperature and these times) is limited to reflow soldering method which is stipulated on the specification.

2) Chips should be mounted, shortly after a solder is on a P.C.Board.

Reflow soldering



5-3. Recommended soldering peak temp and peak temp duration

Pb free solder is recommended, but if Sn-37Pb must be used, refer to below.

Temp./Duration Solder	Reflow soldering	
	Peak temp(°C)	Duration(sec.)
Lead Free Solder	260 max.	10 max.
Sn-Pb Solder	230 max.	20 max.

Recommended solder compositions

Lead Free Solder : Sn-3.0Ag-0.5Cu

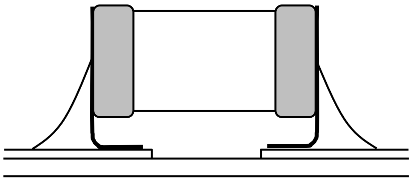
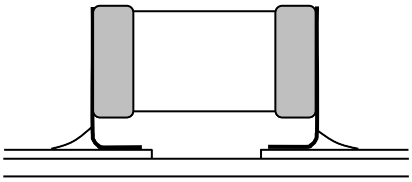
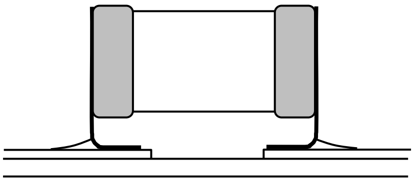
5-4. Avoiding thermal shock

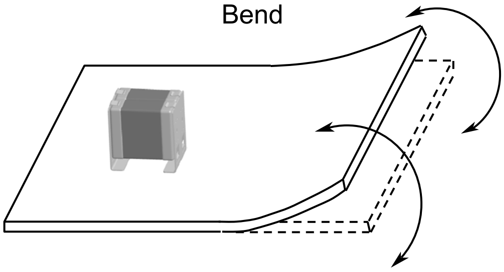
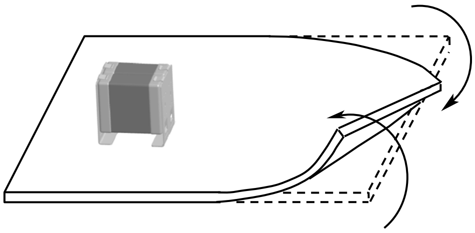
1) Preheating condition

Soldering	Temp. (°C)
Reflow soldering	ΔT ≦ 130

2) Cooling condition

Natural cooling using air is recommended. If the chips are dipped into a solvent for cleaning, the temperature difference (ΔT) must be less than 100°C.

No.	Process	Condition
5	Soldering	5-5. Amount of solder Excessive solder will induce higher tensile force in chip capacitor when temperature changes and it may result in chip cracking. In sufficient solder may detach the capacitor from the P.C.board. Excessive solder  Higher tensile force in chip capacitor to cause crack Adequate  Insufficient solder  Low robustness may cause contact failure or chip capacitor comes off the P.C.board. 5-6. Sn-Zn solder Sn-Zn solder affects product reliability. Please contact TDK in advance when utilize Sn-Zn solder. 5-7. Countermeasure for tombstone The misalignment between the mounted positions of the capacitors and the land patterns should be minimized. The tombstone phenomenon may occur especially the capacitors are mounted (in longitudinal direction) in the same direction of the reflow soldering. (Refer to JEITA RCR-2335C Annex A (Informative) Recommendations to prevent the tombstone phenomenon) 5-8. Other notes related to soldering Do not reuse products that have been removed with a soldering iron. Also, mounting this product with a soldering iron is not guaranteed.

No.	Process	Condition
6	Cleaning	1) If an unsuitable cleaning fluid is used, flux residue or some foreign articles may stick to chip capacitor surface to deteriorate especially the insulation resistance. 2) If cleaning condition is not suitable, it may damage the chip capacitor.
		2)-1. Insufficient washing (1) Terminal electrodes may corrode by Halogen in the flux. (2) Halogen in the flux may adhere on the surface of capacitor, and lower the insulation resistance. (3) Water soluble flux has higher tendency to have above mentioned problems (1) and (2). 2)-2. Excessive washing When ultrasonic cleaning equipment is used, excessive ultrasonic power or direct vibration transfer to a printed wiring board may generate a resonant vibration in the board. This may cause a crack in a capacitor or its solder joints to the board and degradation in the terminal strength of the capacitor. In order to avoid this, the following cleaning conditions are recommended. Power : 20 W/ℓ max. Frequency : 40 kHz max. Washing time : 5 minutes max. 2)-3. If the cleaning fluid is contaminated, density of Halogen increases, and it may bring the same result as insufficient cleaning.
7	Coating and molding of the P.C.board	1) When the P.C.board is coated, please verify the quality influence on the product. 2) Please verify carefully that there is no harmful decomposing or reaction gas emission during curing which may damage the chip capacitor. 3) Please verify the curing temperature.
8	Handling after chip mounted ⚠ Caution	1) Please pay attention not to bend or distort the P.C.board after soldering in handling otherwise the chip capacitor may crack. Bend  Twist 

<table>
<tr><th>No.</th><th>Process</th><th>Condition</th></tr>
<tr><td>8</td><td>Handling after chip mounted
⚠ Caution</td><td>

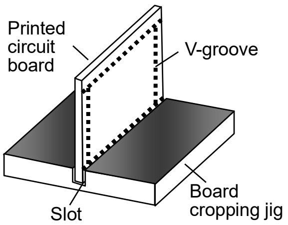
2) Printed circuit board cropping should not be carried out by hand, but by using the proper tooling. Printed circuit board cropping should be carried out using a board cropping jig as shown in the following figure or a board cropping apparatus to prevent inducing mechanical stress on the board.

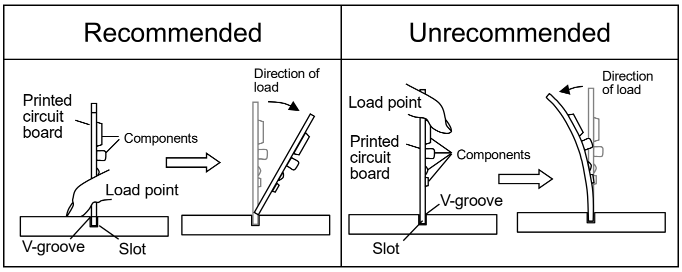
(1)Example of a board cropping jig

Recommended example: The board should be pushed from the back side, close to the cropping jig so that the board is not bent and the stress applied to the capacitor is compressive.

Unrecommended example: If the pushing point is far from the cropping jig and the pushing direction is from the front side of the board, large tensile stress is applied to the capacitor, which may cause cracks.

Outline of jig



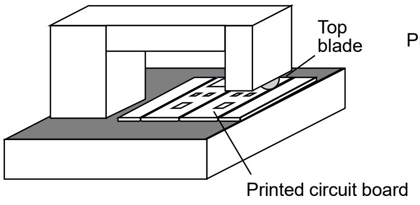


(2)Example of a board cropping machine

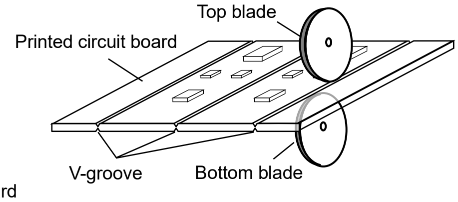
An outline of a printed circuit board cropping machine is shown below. The top and bottom blades are aligned with one another along the lines with the V-grooves on printed circuit board when cropping the board.

Unrecommended example: Misalignment of blade position between top and bottom, right and left, or front and rear blades may cause a crack in the capacitor.

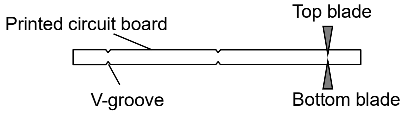
Outline of machine

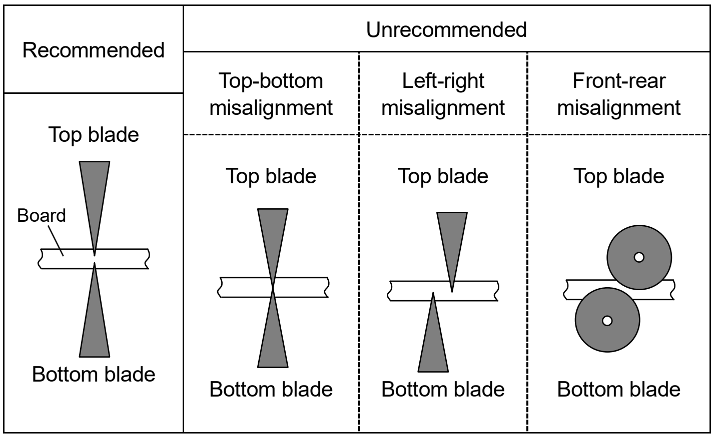


Principle of operation

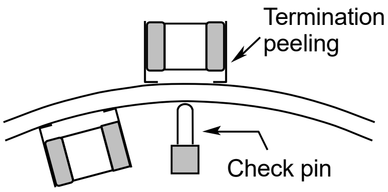
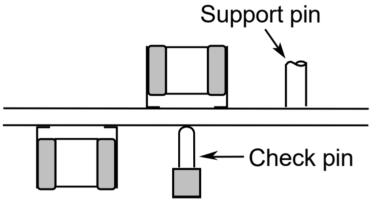
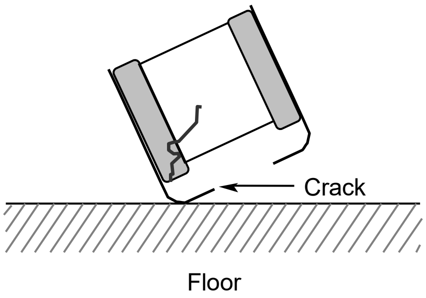


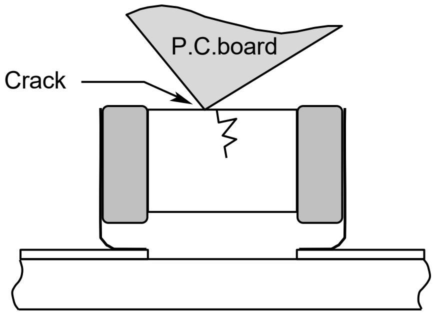
Cross-section diagram





</td></tr>
</table>

<table>
<tr><th>No.</th><th>Process</th><th>Condition</th></tr>
<tr><td>8</td><td>Handling after chip mounted
⚠ Caution</td><td>3) When functional check of the P.C.board is performed, check pin pressure tends to be adjusted higher for fear of loose contact. But if the pressure is excessive and bend the P.C.board, it may crack the chip capacitor or peel the terminations off. Please adjust the check pins not to bend the P.C.board.
<table>
<tr><th>Item</th><th>Not recommended</th><th>Recommended</th></tr>
<tr><td>Board bending</td><td>
</td><td>
</td></tr>
</table></td></tr>
<tr><td>9</td><td>Handling of loose chip capacitor</td><td>1) If dropped the chip capacitor may crack. Once dropped do not use it. Especially, the large case sized chip capacitor is tendency to have cracks easily, so please handle with care.


2) Piling the P.C.board after mounting for storage or handling, the corner of the P.C. board may hit the chip capacitor of another board to cause crack.

</td></tr>
<tr><td>10</td><td>Capacitance aging</td><td>The capacitors have aging in the capacitance. They may not be used in precision time constant circuit. In case of the time constant circuit, the evaluation should be done well.</td></tr>
<tr><td>11</td><td>Estimated life and estimated failure rate of capacitors</td><td>As per the estimated life and the estimated failure rate depend on the temperature and the voltage. This can be calculated by the equation described in JEITA RCR-2335C Annex F (Informative) Calculation of the estimated lifetime and the estimated failure rate (Voltage acceleration coefficient : 3 multiplication rule, Temperature acceleration coefficient : 10°C rule)
The failure rate can be decreased by reducing the temperature and the voltage but they will not be guaranteed.</td></tr>
</table>

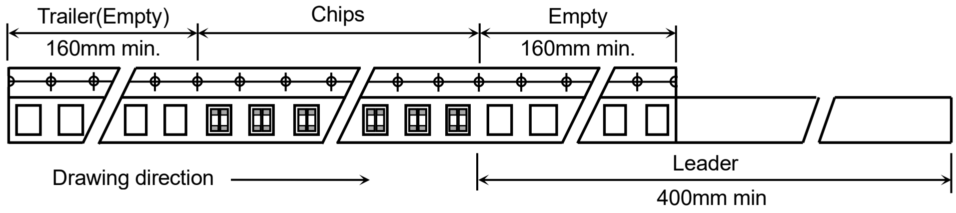
No.	Process	Condition
12	Caution during operation of equipment	1) A capacitor shall not be touched directly with bare hands during operation in order to avoid electric shock. Electric energy held by the capacitor may be discharged through the human body when touched with a bare hand. Even when the equipment is off, a capacitor may stay charged. The capacitor should be handled after being completely discharged using a resistor. 2) The terminals of a capacitor shall not be short-circuited by any accidental contact with a conductive object. A capacitor shall not be exposed to a conductive liquid such as an acid or alkali solution. A conductive object or liquid, such as acid and alkali, between the terminals may lead to the breakdown of a capacitor due to short circuit 3) Confirm that the environment to which the equipment will be exposed during transportation and operation meets the specified conditions. Do not to use the equipment in the following environments. (1) Environment where a capacitor is spattered with water or oil (2) Environment where a capacitor is exposed to direct sunlight (3) Environment where a capacitor is exposed to Ozone, ultraviolet rays or radiation (4) Environment where a capacitor exposed to corrosive gas(e.g. hydrogen sulfide, sulfur dioxide, chlorine. ammonia gas etc.) (5) Environment where a capacitor exposed to vibration or mechanical shock exceeding the specified limits. (6) Atmosphere change with causes condensation
13	Others ⚠ Caution	The products listed on this specification sheet are intended for use in general electronic equipment (AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition. The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet. If you intend to use the products in the applications listed below or if you have special requirements exceeding the range or conditions set forth in this specification, please contact us. (1) Aerospace/Aviation equipment (2) Transportation equipment (cars, electric trains, ships, etc.) (3) Medical equipment (Excepting Pharmaceutical Affairs Law classification Class1,2) (4) Power-generation control equipment (5) Atomic energy-related equipment (6) Seabed equipment (7) Transportation control equipment (8) Public information-processing equipment (9) Military equipment (10) Electric heating apparatus, burning equipment (11) Disaster prevention/crime prevention equipment (12) Safety equipment (13) Other applications that are not considered general-purpose applications When designing your equipment even for general-purpose applications, you are kindly requested to take into consideration securing protection circuit/device or providing backup circuits in your equipment.

11. TAPE PACKAGING SPECIFICATION

1. CONSTRUCTION AND DIMENSION OF TAPING

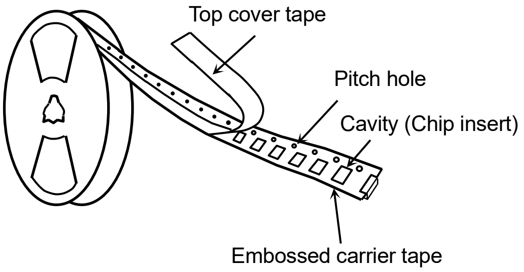
1-1. Dimensions of carrier tape
According to Appendix 3.

1-2. Empty part and leader of taping



1-3. Dimensions of reel
According to Appendix 4.

1-4. Structure of taping



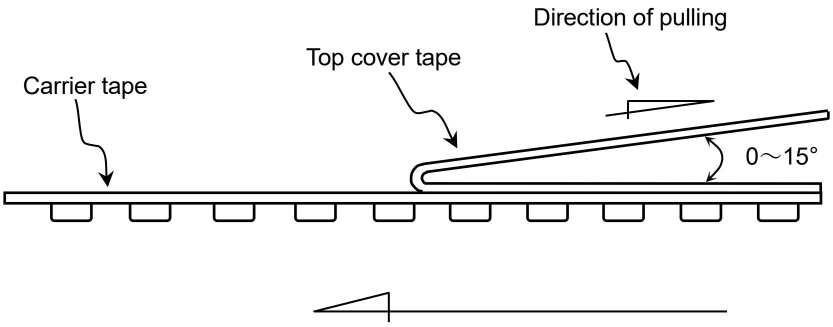
2. CHIP QUANTITY

Please refer to detail page on TDK web.

3. PERFORMANCE SPECIFICATIONS

3-1. Fixing peeling strength (top cover tape)

0.05N < Peeling strength < 0.7N



3-2. Carrier tape shall be flexible enough to be wound around a minimum radius of 30mm with components in tape.

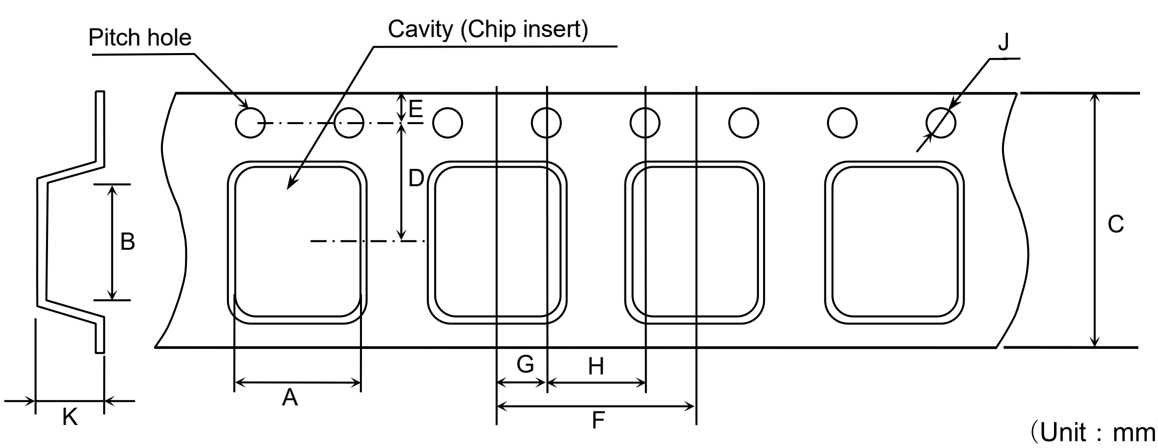
3-3. The missing of components shall be less than 0.1%

3-4. Components shall not stick to fixing tape.

3-5. When removing the cover tape, there shall not be difficulties by unfitting clearance gap, burrs and crushes of cavities. Also the sprocket holes shall not be covered by absorbing dust into the suction nozzle.

Appendix 3

Plastic Tape



(Unit : mm)

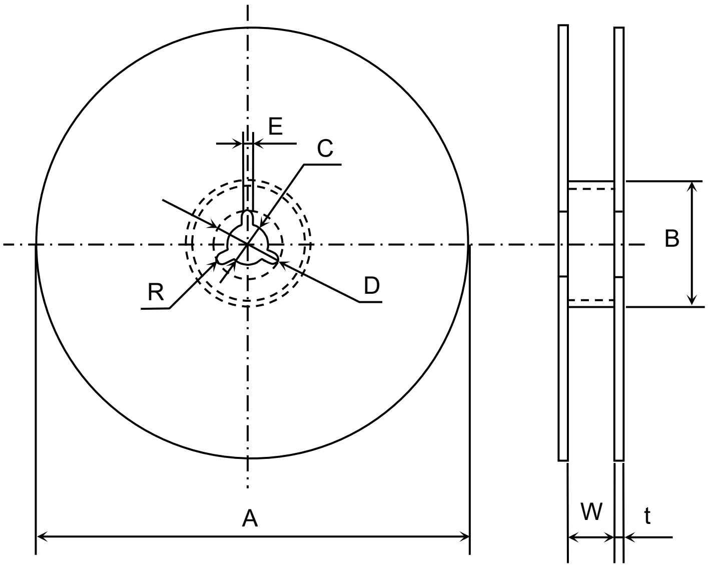
Symbol / Type	A	B	C	D	E	F
CAA572	(5.30)	(6.40) *1 (6.65)	16.0±0.30	7.50±0.10	1.75±0.10	12.00±0.10
CAA573	(6.40) *2 (6.68)	*2 (7.75) (7.80)				

Symbol / Type	G	H	J	K
CAA572	2.00±0.10	4.00±0.10	$\varnothing 1.50^{+0.1}_{0}$	7.10 max.
CAA573				

(   ) Referenced value.
*1 Applied to CAA572X7R1H(1V)476M, CAA572X7R1E(1V)107M.
*2 Applied to CAA573X7R1H(1V)686M, CAA573X7R1E(1V)157M.

Appendix 4

(Material : Polystyrene)



(Unit : mm)

Symbol	A	B	C	D	E	W
Dimension	⌀382 max. (Nominal⌀330)	⌀50 min.	⌀13±0.5	⌀21±0.8	2.0±0.5	17.5±1.5

Symbol	t	R
Dimension	2.0±0.5	1.0